- Package Options Include Plastic "Small Outline" Packages, Ceramic Chip Carriers and Flat Packages, and Plastic and Ceramic DIPs
- Dependable Texas Instruments Quality and Reliability

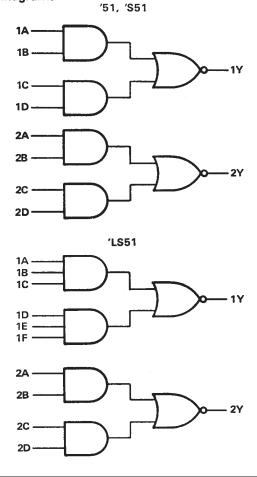
description

The '51 and 'S51 contain two independent 2-wide 2-input AND-OR-INVERT gates. They perform the Boolean function $Y = \overline{AB + CD}$.

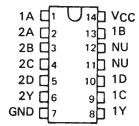
The 'LS51 contains one 2-wide 3-input and one 2-wide 2-input AND-OR-INVERT gates. They perform the Boolean functions $1Y = \overline{(1A \cdot 1B \cdot 1C) + (1D \cdot 1E \cdot 1F)}$ and $2Y = \overline{(2A \cdot 2B) + (2C \cdot 2D)}$.

The SN5451, SN54LS51, and SN54S51 are characterized for operation over the full military temperature range of -55° C to 125°C. The SN7451, SN74LS51 and SN74S51 are characterized for operation from 0°C to 70°C.

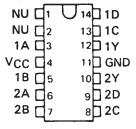
logic diagrams



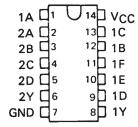
SN5451 . . . J PACKAGE SN54S51 . . . J OR W PACKAGE SN7451 . . . N PACKAGE SN74S51 . . . D OR N PACKAGE (TOP VIEW)



SN5451 . . . W PACKAGE (TOP VIEW)



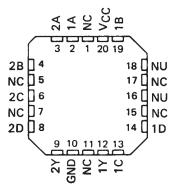
SN54LS51 . . . J OR W PACKAGE SN74LS51 . . . D OR N PACKAGE (TOP VIEW)



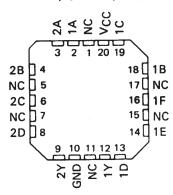
NC- No internal connection
NU - Make no external connection



SN54S51 . . . FK PACKAGE (TOP VIEW)

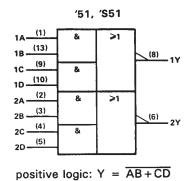


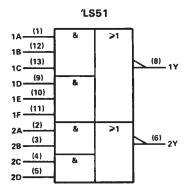
SN54LS51 . . . FK PACKAGE (TOP VIEW)



NC - No internal connection NU - Make no external connection

logic symbols†





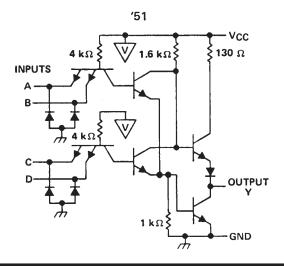
positive logic:

$$1Y = \overline{(1A \cdot 1B \cdot 1C) + (1D \cdot 1E \cdot 1F)}$$

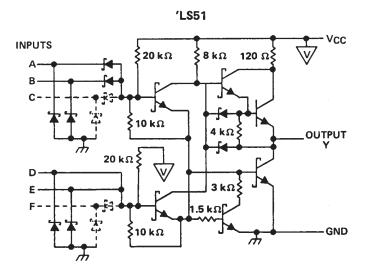
$$2Y = \overline{(2A \cdot 2B) + (2C \cdot 2D)}$$

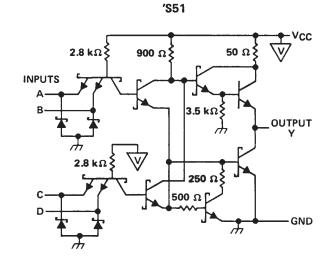
†These symbols are in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12. Pin numbers shown are for D, J, N, and W packages.

schematics









absolute maximum ratings over operating free-air temperature range (unless otherwise noted)

Supply voltage, VCC (See Note 1): '	51, 'LS51, 'S51	7 V
Input voltage: '51, 'S51		5.5 V
′LS51		7 V
Operating free-air temperature range	SN54'	-55°C to 125°C
	SN74'	0°C to 70°C
Storage temperature range		-65°C to 150°C

NOTE 1: Voltage values are with respect to network ground terminal.



recommended operating conditions

			SN5451			SN7451			
		MIN	NOM	MAX	MIN	NOM	MAX	UNIT	
Vcc	Supply voltage	4.5	5	5.5	4.75	5	5.25	٧	
VIH	High-level input voltage	2			2			V	
VIL	Low-level input voltage			0.8			0.8	V	
Іон	High-level output current			- 0.4			- 0.4	mΑ	
lOL	Low-level output current			16			16	mA	
TA	Operating free-air temperature	– 55		125	0		70	°C	

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

							-	UNIT		
PARAMETER		TEST CONDI	TIONS †	MIN	TYP‡	MAX	MIN	TYP ‡	MAX	UNII
VIK	V _{CC} = MIN, I	_I = - 12 mA				- 1.5			1.5	٧
Voн		/IL = 0.8 V,	I _{OH} = - 0.4 mA	2.4	3.4		2.4	3.4		>
VOL	V _{CC} = MIN, V	/ _{IH} = 2 V,	I _{OL} = 16 mA		0.2	0.4		0.2	0.4	>
lj.	V _{CC} = MAX, V	/ _I = 5.5 V				1			1	mA
ин	V _{CC} = MAX, V	/ ₁ = 2.4 V				40			40	μΑ
I _I L	V _{CC} = MAX, V	/ _I = 0.4 V				– 1.6			– 1.6	mA
1058	V _{CC} = MAX			- 20		- 55	- 18		- 55	mA
1ссн	V _{CC} = MAX, V	/ _I = 0 V			4	8		4	8	mA
ICCL	V _{CC} = MAX, S	See Note 2			7.4	14		7.4	14	mA

[†] For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.

NOTE 2: All inputs of one AND gate at 4.5 V, all others at GND.

switching characteristics, V_{CC} = 5 V, T_A = 25°C (see note 3)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	TEST CON	DITIONS	MIN	TYP	MAX	UNIT
tPLH tPHL	Any	Y	R _L = 400 Ω,	C _L = 15 pF		13 8	22 15	ns

NOTE 3: Load circuits and voltage waveforms are shown in Section 1.



[‡] All typical values are at V_{CC} = 5 V, T_A = 25° C. § Not more than one output should be shorted at a time.

recommended operating conditions

			SN54LS51			SN74LS	51	UNIT
1		MIN	NOM	MAX	MIN	NOM	MAX	OWIT
Vcc	Supply voltage	4.5	5	5.5	4.75	5	5.25	V
VIH	High-level input voltage	2			2			V
VIL	Low-level input voltage			0.7			8.0	٧
10Н	High-level output current			-0.4			-0.4	mA
loL	Low-level output current			4			8	mA
TA	Operating free-air temperature	- 55		125	0		70	°C

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

242445752		TEOT 00415	ITIONS 4	S	N54LS	51	s	N74LS	51	UNIT
PARAMETER		TEST COND	ILLIONS T	MIN	TYP ‡	MAX	MIN	TYP‡	MAX	UNIT
VIK	V _{CC} = MIN,	I _I = - 18 mA				– 1. 5			– 1.5	· V
Voн	V _{CC} = MIN,	VIL = MAX,	I _{OH} = - 0.4 mA	2.5	3.4		2.7	3.4		>
V	V _{CC} = MIN,	V _{IH} = 2 V,	IOL = 4 mA		0.25	0.4		0.25	0.4	V
VOL	V _{CC} = MIN,	V _{IH} = 2 V,	I _{OL} = 8 mA					0.35	0.5	· ·
lj	V _{CC} = MAX,	V _I = 7 V				0.1			0.1	mA
IН	V _{CC} = MAX,	V _I = 2.7 V				20			20	μΑ
lir.	V _{CC} = MAX,	V ₁ = 0.4 V				- 0.4			- 0.4	mA
IOS§	V _{CC} = MAX			- 20		- 100	- 20		100	mA
Іссн	V _{CC} = MAX,	V _I = 0 V			8.0	1.6		8.0	1.6	mA
ICCL	V _{CC} = MAX,	See Note 2			1,4	2,8		1.4	2.8	mA

[†] For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.

NOTE 2: All inputs of one AND gate at 4.5 V, all others at GND.

switching characteristics, $V_{CC} = 5 \text{ V}$, $T_A = 25^{\circ}\text{C}$ (see note 3)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	TEST CON	DITIONS	MIN TYP	MAX	UNIT
tPLH	0		B3k0	C. = 15 pE	12	20	ns
tPHL	Any	τ	$R_L = 2 k\Omega$,	C _L = 15 pF	12.5	20	กร

NOTE 3: Load circuits and voltage waveforms are shown in Section 1.



[‡] All typical values are at $V_{CC} = 5 \text{ V}$, $T_A = 25 ^{\circ} \text{C}$.

[§] Not more than one output should be shorted at a time, and the duration of the short-circuit should not exceed one second.

recommended operating conditions

		SN54S51				SN74S5	1	UNIT
		MIN	NOM	MAX	MIN	NOM	MAX	ONT
Vcc	Supply voltage	4.5	5	5.5	4.75	5	5.25	V
VIH	High-level input voltage	2			2			V
VIL	Low-level input voltage			8.0			0.8	V
loH	High-level output current			- 1			- 1	mA
lOL	Low-level output current			20			20	mA
TA	Operating free-air temperature	- 55		125	0		70	°C

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

				,	SN54S5	1		SN74S5	1	UNIT
PARAMETER		TEST COND	ITIONS †	MIN	TYP ‡	MAX	MIN	TYP‡	MAX	UNIT
VIK	V _{CC} = MIN,	I _I = 18 mA				1.2			1.2	V
Voн	V _{CC} = MIN,	V _{IL} = 0.8 V,	I _{OH} = -1 mA	2.5	3.4		2.7	3.4		V
VOL	V _{CC} = MIN,	V _{IH} = 2 V,	I _{OL} = 20 mA			0.5			0.5	V
I _I	V _{CC} = MAX,	V ₁ = 5.5 V				1			1	mA
ЧН	V _{CC} = MAX,	V _I = 2.7 V				50			50	μΑ
I _Ι Ε	V _{CC} = MAX,	V ₁ = 0.5 V				-2			-2	mA
loss	V _{CC} = MAX			- 40		- 100	40		100	mA
Іссн	V _{CC} = MAX,	V _I = 0 V			8.2	17.8		8.2	17.8	mA
ICCL	V _{CC} = MAX,	See Note 2			13.6	22		13.6	22	mA

[†] For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.

NOTE 2: All inputs of one AND gate at 4.5 V, all others at GND.

switching characteristics, $V_{CC} = 5 \text{ V}$, $T_A = 25^{\circ}\text{C}$ (see note 3)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	TEST CON	DITIONS	MIN TYP	MAX	UNIT
tPLH			D - 200 C	C = 15 oF	3.5	5.5	ns
tPHL	_		R _L = 280 Ω,	C _L = 15 pF	3.5	5.5	ns
^t PLH	Any	Y	R _L = 280 Ω,	C ₁ = 50 pF	5		ns
t _{PHL}			11, 200 32,	o <u>r</u> 00 h.	5.5		ns

NOTE 3: Load circuits and voltage waveforms are shown in Section 1.



[‡] All typical values are at $V_{CC} = 5 \text{ V}$, $T_A = 25^{\circ}\text{C}$.

[§] Not more than one output should be shorted at a time, and the duration of the short-circuit should not exceed one second.



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PACKAGING INFORMATION

Orderable Device	Status	Package Type	Package Drawing	Pins	Package Qty	Eco Plan	Lead finish/ Ball material	MSL Peak Temp	Op Temp (°C)	Device Marking (4/5)	Samples
JM38510/00502BCA	ACTIVE	CDIP	J	14	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	JM38510/ 00502BCA	Samples
JM38510/07401BCA	ACTIVE	CDIP	J	14	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	JM38510/ 07401BCA	Samples
JM38510/07401BDA	ACTIVE	CFP	W	14	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	JM38510/ 07401BDA	Samples
JM38510/30401BCA	ACTIVE	CDIP	J	14	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	JM38510/ 30401BCA	Samples
JM38510/30401BCA	ACTIVE	CDIP	J	14	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	JM38510/ 30401BCA	Samples
M38510/00502BCA	ACTIVE	CDIP	J	14	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	JM38510/ 00502BCA	Samples
M38510/00502BCA	ACTIVE	CDIP	J	14	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	JM38510/ 00502BCA	Samples
M38510/07401BCA	ACTIVE	CDIP	J	14	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	JM38510/ 07401BCA	Samples
M38510/07401BDA	ACTIVE	CFP	W	14	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	JM38510/ 07401BDA	Samples
M38510/30401BCA	ACTIVE	CDIP	J	14	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	JM38510/ 30401BCA	Samples
M38510/30401BCA	ACTIVE	CDIP	J	14	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	JM38510/ 30401BCA	Samples
SN5451J	ACTIVE	CDIP	J	14	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	SN5451J	Samples
SN5451J	ACTIVE	CDIP	J	14	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	SN5451J	Samples
SN54LS51J	ACTIVE	CDIP	J	14	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	SN54LS51J	Samples
SN54LS51J	ACTIVE	CDIP	J	14	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	SN54LS51J	Samples
SN54S51J	ACTIVE	CDIP	J	14	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	SN54S51J	Samples
SN74LS51D	ACTIVE	SOIC	D	14	50	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	0 to 70	LS51	Samples





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Orderable Device	Status	Package Type	Package Drawing	Pins	Package Qty	Eco Plan	Lead finish/ Ball material	MSL Peak Temp	Op Temp (°C)	Device Marking (4/5)	Samples
SN74LS51D	ACTIVE	SOIC	D	14	50	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	0 to 70	LS51	Samples
SN74LS51DR	ACTIVE	SOIC	D	14	2500	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	0 to 70	LS51	Samples
SN74LS51DR	ACTIVE	SOIC	D	14	2500	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	0 to 70	LS51	Samples
SN74LS51N	ACTIVE	PDIP	N	14	25	RoHS & Green	NIPDAU	N / A for Pkg Type	0 to 70	SN74LS51N	Samples
SN74LS51N	ACTIVE	PDIP	N	14	25	RoHS & Green	NIPDAU	N / A for Pkg Type	0 to 70	SN74LS51N	Samples
SN74LS51NSR	ACTIVE	SO	NS	14	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	0 to 70	74LS51	Samples
SN74LS51NSR	ACTIVE	SO	NS	14	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	0 to 70	74LS51	Samples
SN74S51D	ACTIVE	SOIC	D	14	50	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	0 to 70	S51	Samples
SN74S51D	ACTIVE	SOIC	D	14	50	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	0 to 70	S51	Samples
SN74S51N	ACTIVE	PDIP	N	14	25	RoHS & Green	NIPDAU	N / A for Pkg Type	0 to 70	SN74S51N	Samples
SN74S51N	ACTIVE	PDIP	N	14	25	RoHS & Green	NIPDAU	N / A for Pkg Type	0 to 70	SN74S51N	Samples
SNJ5451J	ACTIVE	CDIP	J	14	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	SNJ5451J	Samples
SNJ5451J	ACTIVE	CDIP	J	14	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	SNJ5451J	Samples
SNJ5451W	ACTIVE	CFP	W	14	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	SNJ5451W	Samples
SNJ5451W	ACTIVE	CFP	W	14	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	SNJ5451W	Samples
SNJ54LS51J	ACTIVE	CDIP	J	14	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	SNJ54LS51J	Samples
SNJ54LS51J	ACTIVE	CDIP	J	14	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	SNJ54LS51J	Samples
SNJ54LS51W	ACTIVE	CFP	W	14	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	SNJ54LS51W	Samples
SNJ54LS51W	ACTIVE	CFP	W	14	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	SNJ54LS51W	Samples

PACKAGE OPTION ADDENDUM

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Orderable Device	Status	Package Type	Package Drawing	Pins	Package Qty	Eco Plan	Lead finish/ Ball material	MSL Peak Temp	Op Temp (°C)	Device Marking (4/5)	Samples
SNJ54S51FK	ACTIVE	LCCC	FK	20	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	SNJ54S 51FK	Samples
SNJ54S51J	ACTIVE	CDIP	J	14	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	SNJ54S51J	Samples

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) RoHS: TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".

RoHS Exempt: TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.

Green: TI defines "Green" to mean the content of Chlorine (CI) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

- (3) MSL, Peak Temp. The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.
- (4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.
- (5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.
- (6) Lead finish/Ball material Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

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PACKAGE OPTION ADDENDUM

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OTHER QUALIFIED VERSIONS OF SN54LS51, SN54S51, SN74LS51, SN74S51:

● Catalog : SN74LS51, SN74S51

Military: SN54LS51, SN54S51

NOTE: Qualified Version Definitions:

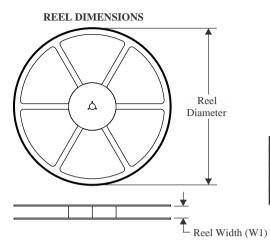
• Catalog - TI's standard catalog product

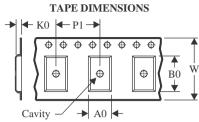
• Military - QML certified for Military and Defense Applications

PACKAGE MATERIALS INFORMATION

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TAPE AND REEL INFORMATION





A0	Dimension designed to accommodate the component width
В0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal

Device	Package Type	Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74LS51DR	SOIC	D	14	2500	330.0	16.4	6.5	9.0	2.1	8.0	16.0	Q1
SN74LS51NSR	so	NS	14	2000	330.0	16.4	8.2	10.5	2.5	12.0	16.0	Q1

PACKAGE MATERIALS INFORMATION

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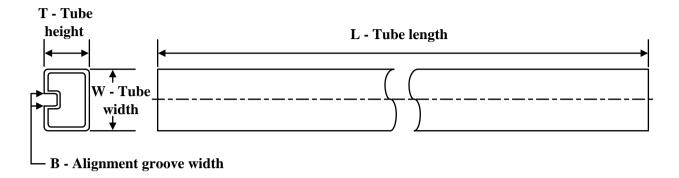
*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74LS51DR	SOIC	D	14	2500	356.0	356.0	35.0
SN74LS51NSR	so	NS	14	2000	356.0	356.0	35.0

PACKAGE MATERIALS INFORMATION

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TUBE



*All dimensions are nominal

Device	Package Name	Package Type	Pins	SPQ	L (mm)	W (mm)	T (µm)	B (mm)
JM38510/07401BDA	W	CFP	14	1	506.98	26.16	6220	NA
M38510/07401BDA	W	CFP	14	1	506.98	26.16	6220	NA
SN74LS51D	D	SOIC	14	50	506.6	8	3940	4.32
SN74LS51N	N	PDIP	14	25	506	13.97	11230	4.32
SN74LS51N	N	PDIP	14	25	506	13.97	11230	4.32
SN74S51D	D	SOIC	14	50	506.6	8	3940	4.32
SN74S51N	N	PDIP	14	25	506	13.97	11230	4.32
SN74S51N	N	PDIP	14	25	506	13.97	11230	4.32
SNJ5451W	W	CFP	14	1	506.98	26.16	6220	NA
SNJ54LS51W	W	CFP	14	1	506.98	26.16	6220	NA
SNJ54S51FK	FK	LCCC	20	1	506.98	12.06	2030	NA

MECHANICAL DATA

NS (R-PDSO-G**)

14-PINS SHOWN

PLASTIC SMALL-OUTLINE PACKAGE



- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.



W (R-GDFP-F14)

CERAMIC DUAL FLATPACK



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. This package can be hermetically sealed with a ceramic lid using glass frit.
- D. Index point is provided on cap for terminal identification only.
- E. Falls within MIL STD 1835 GDFP1-F14



8.89 x 8.89, 1.27 mm pitch

LEADLESS CERAMIC CHIP CARRIER

This image is a representation of the package family, actual package may vary. Refer to the product data sheet for package details.



CERAMIC DUAL IN LINE PACKAGE



Images above are just a representation of the package family, actual package may vary. Refer to the product data sheet for package details.

4040083-5/G





CERAMIC DUAL IN LINE PACKAGE



- 1. All controlling linear dimensions are in inches. Dimensions in brackets are in millimeters. Any dimension in brackets or parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
- 2. This drawing is subject to change without notice.
- 3. This package is hermitically sealed with a ceramic lid using glass frit.
- His package is remitted by sealed with a certain is using glass int.
 Index point is provided on cap for terminal identification only and on press ceramic glass frit seal only.
 Falls within MIL-STD-1835 and GDIP1-T14.



CERAMIC DUAL IN LINE PACKAGE



D (R-PDSO-G14)

PLASTIC SMALL OUTLINE



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.006 (0,15) each side.
- Body width does not include interlead flash. Interlead flash shall not exceed 0.017 (0,43) each side.
- E. Reference JEDEC MS-012 variation AB.



D (R-PDSO-G14)

PLASTIC SMALL OUTLINE



- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Publication IPC-7351 is recommended for alternate designs.
- D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525 for other stencil recommendations.
- E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.



N (R-PDIP-T**)

PLASTIC DUAL-IN-LINE PACKAGE

16 PINS SHOWN



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
- The 20 pin end lead shoulder width is a vendor option, either half or full width.



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